

Q1
[Please amend claim 16 as follows:]

16. (Amended) The method of claim 15, wherein one of said semiconductor dies is mounted back to back on the other of said semiconductor dies.

[Please amend claim 17 as follows:]

17. (Amended) The method of claim 16, wherein one of said semiconductor dies is adhered to the other of semiconductor dies by an adhesive layer.

Please add the following new claims 32, *et seq.*

sub 32
32. (New) A method for mounting multiple semiconductor dies on a single leadframe, comprising:

stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of one another;
mounting the first semiconductor die on a leadframe; and
mounting the second semiconductor die only on said first semiconductor die.

33. (New) The method of claim 32 including wire bonding the first and second semiconductor dies to the leadframe.

34. (New) The method of claim 32 wherein the first semiconductor die is mounted back to back on the second semiconductor die.

35. (New) The method of claim 34 wherein the first semiconductor die is adhered to the second semiconductor die by an adhesive layer.

REMARKS

The pending claims were rejected under §102 over the Ball patent. The objections under §112 have been cured. The objection to the title has also been cured. The objection to the specification set forth in paragraph 3 is not understood. The claimed invention in this divisional